



	Value	Unit
	60	V
	1.6t	V
	34	A
	11.8	m3
	14.6	m3



Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 48V, V _{GS} = 0V	-	-	1.0	μ
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1.2	1.6	2.1	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	V _{GS} = 10V, I _D = 20A	-	11.3	14.7	mΩ
		V _{GS} = 4.5V, I _D = 15A	-	14.6	19.0	mΩ
Dynamic Characteristics						
R _g	Gate Resistance	f = 1MHz	-	1.8	-	Ω
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 30V, f = 1MHz	542	758	1024	pF
C _{oss}	Output Capacitance		275	385	520	pF
C _{rss}	Reverse Transfer Capacitance		19	26	35	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 30V, I _D = 20A	10	14	19	nC
Q _{gs}	Gate Source Charge		-	2.7	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	3.2	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 30V I _D = 20A, R _{GEN} = 3Ω	-	5.4	-	ns
t _r	Turn-On Rise Time		-	14	-	ns
t _{d(off)}	Turn-Off DelayTime		-	16	-	ns
t _f	Turn-Off Fall Time		-	4.3	-	ns
Body Diode Characteristics						
I _S	Maximum Continuous Body Diode Forward Current		-	-	34	A
I _{SM}	Maximum Pulsed Body Diode Forward Current		-	-	135	A
V _{SD}	Body Diode Forward Voltage	V _{GS} = 0V, I _S = 20A	-		1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 20A, di/dt = 100A/us	16	22	30	ns
Qrr	Body Diode Reverse Recovery Charge		-	11	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 30\text{V}$, $V_{GS} = 10\text{V}$, $R_G = 25\text{ohm}$, $L = 3\text{mH}$, $I_{AS} = 5.6\text{A}$, $V_{DD} = 0\text{V}$ during time in avalanche.
 3. R is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB.
 4. Pulse Test: Pulse Width $\leq$ $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Power De-rating

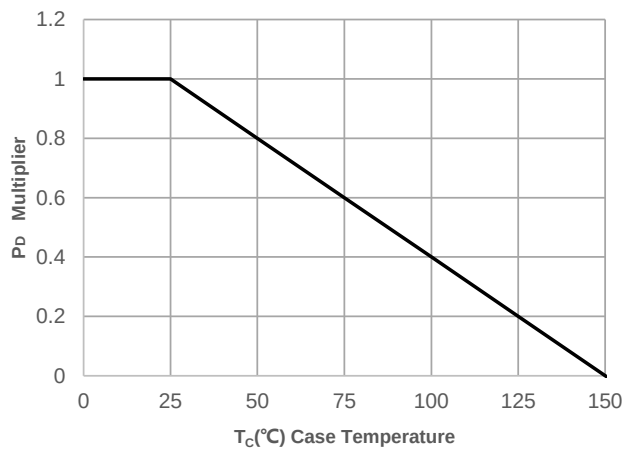
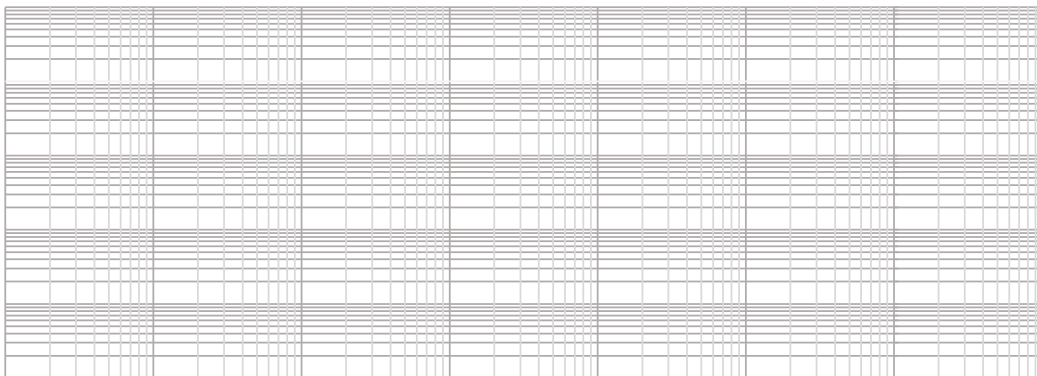
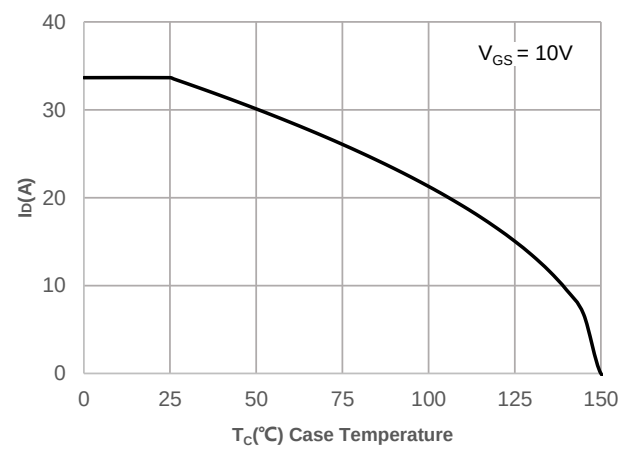
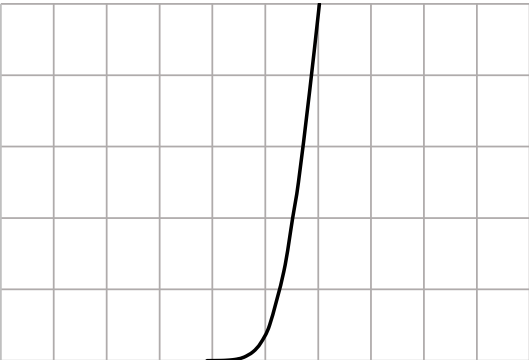
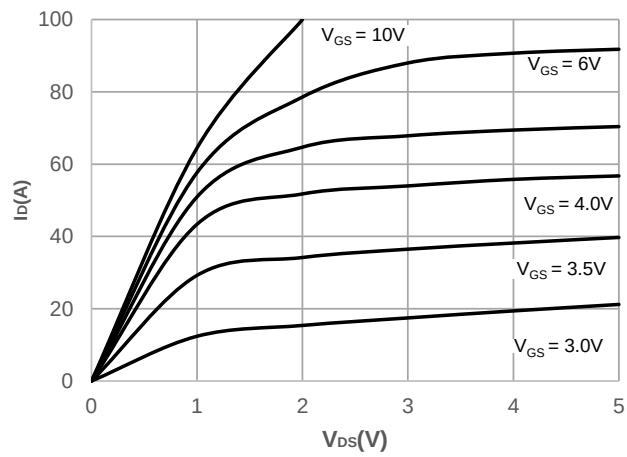


Figure 2: Current De-rating



Typical Performance Characteristics

Figure 5: Output Characteristics



Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

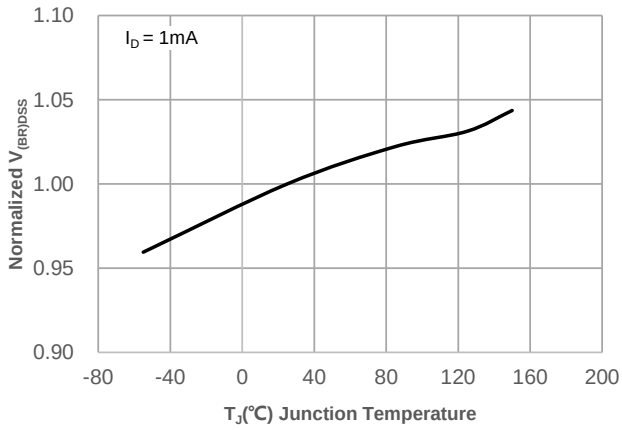


Figure 12: Normalized on Resistance vs. Junction Temperature

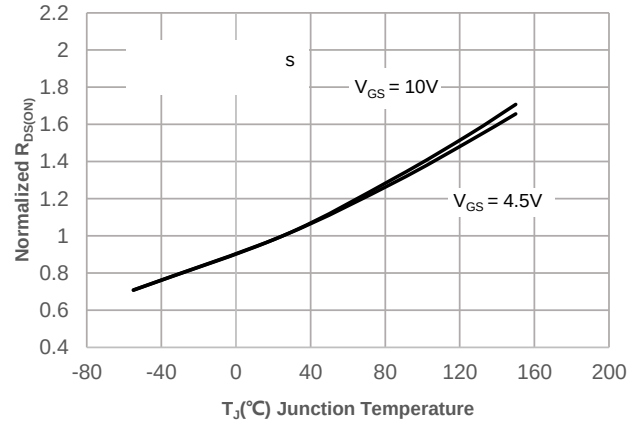


Figure 14: $R_{DS(ON)}$ vs. V_{GS}

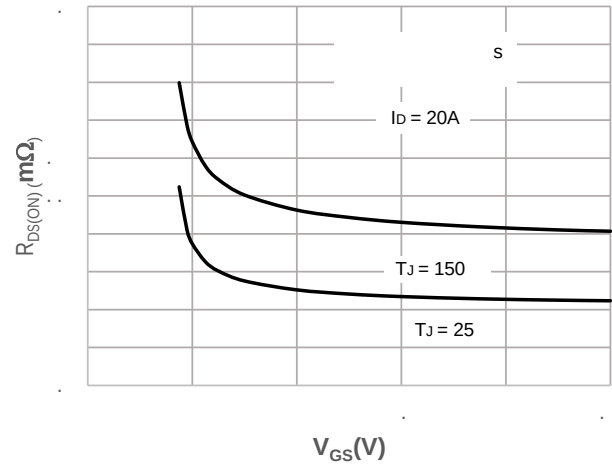
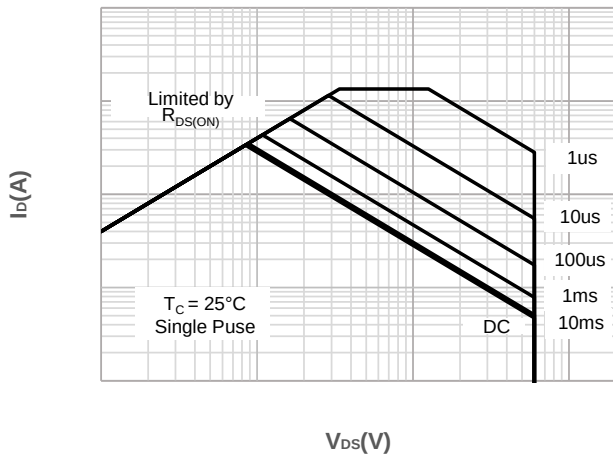


Figure 15: Maximum Safe Operating Area



Test Circuit



Figure 1: Gate Charge Test Circuit & Waveform

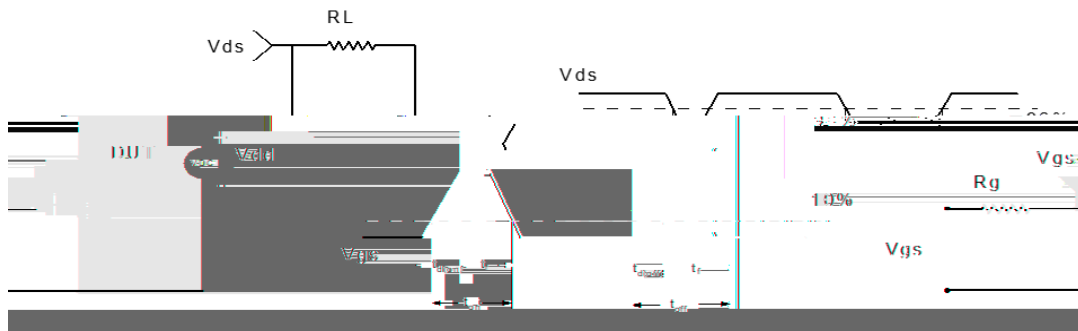


Figure 2: Resistive Switching Test Circuit & Waveform

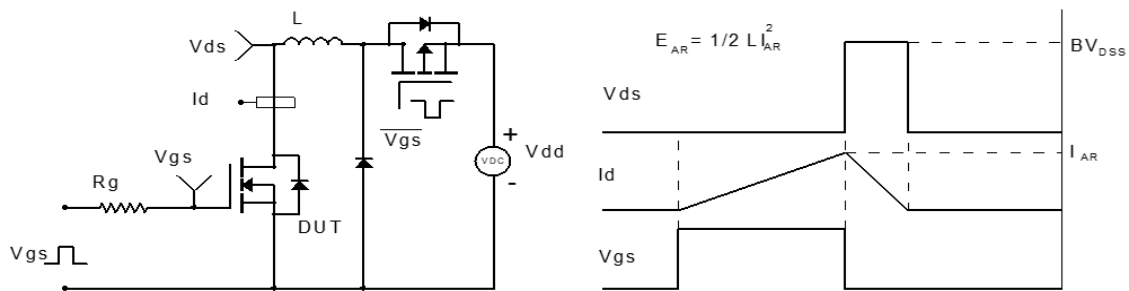


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

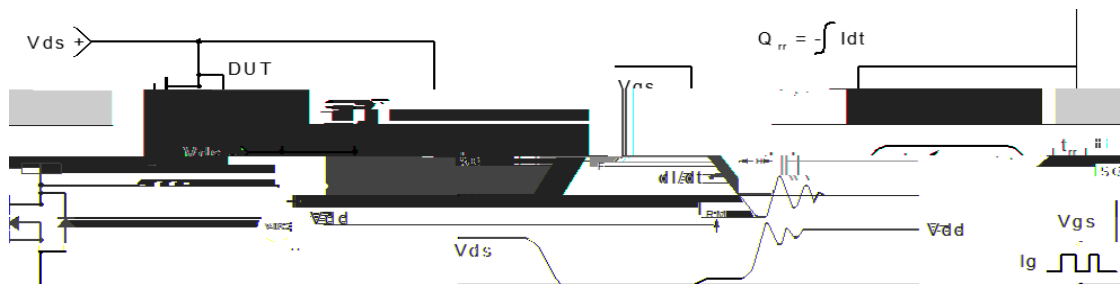


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN3X3-8L-D)

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